

ABSTRACT

A die-sorting sheet includes a pressure-sensitive
5 adhesive layer exposed on an outer periphery of the carrier sheet,
and a base film exposed on a central area that is inside the
outer periphery. A method for transporting a chip having an
adhesive layer according to the present invention includes the
steps of: providing the above die-sorting sheet that is fixed
10 with a frame through the pressure-sensitive adhesive layer on
the outer periphery; temporarily attaching a picked up chip
through an adhesive layer thereof onto the base film exposed
on the die-sorting sheet; and transporting the die-sorting sheet
to a subsequent step while the chip is temporarily attached on
15 the sheet through the adhesive layer.